

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.85647	100.0	1
			<b>Subtotal</b>	<b>0.85647</b>	<b>100</b>	<b>1</b>
Wire	Impurity	Non hazardous		0.00001	0.01	0.00001
	Pure metal	Copper (Cu)	7440-50-8	0.06744	99.99	0.07874
			<b>Subtotal</b>	<b>0.06745</b>	<b>100</b>	<b>0.07875</b>
Die Attach		Aromatic Polyester Resin	60088-52-0	0.00278	2.5	0.00325
		Paraffin wax	8002-74-2	0.00779	7.0	0.0091
		Epoxy resin system		0.02227	20.0	0.026
		Silver (Ag)	7440-22-4	0.0785	70.5	0.09165
			<b>Subtotal</b>	<b>0.11134</b>	<b>100</b>	<b>0.13</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02614	0.05	0.03053
	Copper alloy	Zinc (Zn)	7440-66-6	0.05229	0.1	0.06105
	Copper alloy	Iron (Fe)	7439-89-6	1.20261	2.3	1.40415
	Copper alloy	Copper (Cu)	7440-50-8	51.00626	97.55	59.55427
			<b>Subtotal</b>	<b>52.2873</b>	<b>100</b>	<b>61.05</b>
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.48819	100.0	0.57
			<b>Subtotal</b>	<b>0.48819</b>	<b>100</b>	<b>0.57</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.69284	1.5	0.80895
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.38798	9.5	5.12335
	Filler	Silica fused	60676-86-0	40.64655	88.0	47.4584
	Carbon Black	Carbon black	1333-86-4	0.46189	1.0	0.5393
			<b>Subtotal</b>	<b>46.18926</b>	<b>100</b>	<b>53.93</b>
			<b>Total</b>	<b>100.00001</b>	<b>100</b>	<b>116.75875</b>

#### Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.